

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	0	(power near switch\$3) with (driv\$3 near (IC (intergrated near circuit))) with (flip near chip near bond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/23 15:29
L8	0	(power near switch\$3) same (driv\$3 near (IC (intergrated near circuit))) same (flip near chip near bond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/23 15:29
L9	0	(power near switch\$3 near (chip die)) with (driv\$3 near (IC (intergrated near circuit) chip die)) with (flip near chip near bond\$3) .	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/23 15:34
L10	0	(power near switch\$3 near (chip die)) and (driv\$3 near (IC (intergrated near circuit) chip die)) and (flip near chip near bond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/23 15:31
L11	8	(power near (chip die)) and (driv\$3 near (IC (intergrated near circuit) chip die)) and (flip near chip near bond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/23 15:31
L12	0	(power near switch\$3 near (chip die)) with (driv\$3 near (IC (intergrated near circuit) chip die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/23 15:33
L13	129	(power near (chip die)) with (driv\$3 near (IC (intergrated near circuit) chip die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/23 15:35
L14	0	(power near (chip die)) with (driv\$3 near (IC (intergrated near circuit) chip die)) with (flip near chip near bond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/23 15:34

L15	0	(power near (chip die)) with (driv\$3 near (IC (integrated near circuit) chip die)) with (flip near chip near bond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/23 15:34
L16	0	(power near (chip die)) with (driv\$3 near (IC (integrated near circuit) chip die)) with (flip near chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/23 15:34
L17	138	(power near (chip die)) with (driv\$3 near (IC (integrated near circuit) chip die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/23 15:35
L18	2	17 and (flip near chip near bond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/23 15:37
L19	20	17 and (flip near chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/23 15:37
L21	2	10/337,872	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/23 16:30
L22	10	("4697095" "4703483" "4965702" "5475918" "5739582" "5757070" "5777345" "5923957" "6025212" "6291880").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/23 16:31